



GaN HEMT 28V C band 65W, RF Power Transistor

Description

The XTAH75065G4 is a 65W internally matched, C band GaN HEMT, designed up to 7.5GHz, especially 5G NR or LTE application, as well as either Pulse or CW application.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies. **Please notice that both leads at input and output are internally connected to make it as single ended configuration**

- Typical 5.8-6.6GHz RF performance (on narrow band fixture with device soldered)

$V_{DD}=28V$ $I_{DQ}=100mA$, CW

Freq (MHz)	P1dB (W)	P1dB Eff (%)	P1dB Gain (dB)	P3dB (dBm)	P3dB (W)	P3dB Eff (%)
5850	49.3	43.6	9.66	48.46	70.2	48.5
5950	49.6	43.5	10.03	48.58	72.2	48.9
6050	51.0	45.1	10.44	48.67	73.6	50.5
6150	48.5	44.2	10.48	48.52	71.0	49.9
6250	46.9	44.7	10.44	48.36	68.6	50.2
6350	44.7	45.6	10.43	48.12	64.9	51.0
6450	42.5	43.4	10.13	47.96	62.5	49.0
6550	41.6	42.8	9.76	47.8	60.3	47.6
6650	41.8	43.5	9.64	47.84	60.9	48.7

- Typical 6.9-7.4GHz RF performance (on broadband fixture with device soldered)

$V_{DD}=28V$ $I_{DQ}=100mA$, CW

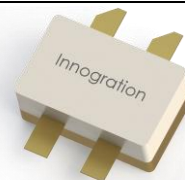
Freq (MHz)	P1dB (W)	P1dB Eff (%)	P1dB Gain (dB)	P3dB (dBm)	P3dB (W)	P3dB Eff (%)
6900	47.3	38.1	10.09	48.14	65.2	41.8
7000	49.0	40.0	10.24	48.22	66.4	43.3
7100	49.6	42.0	10.39	48.25	66.9	45.4
7200	47.4	42.0	10.32	47.95	62.4	44.8
7300	47.6	42.2	10.16	47.91	61.8	44.9
7400	49.3	43.8	10.4	48.03	63.5	46.4

Recommended driver: XTAH78020C6

Applications and Features

- Suitable for wireless communication infrastructure, wideband amplifier, EMC testing, ISM etc.
- High Efficiency and Linear Gain Operations
- Thermally Enhanced Industry Standard Package
- High Reliability Metallization Process
- Excellent thermal Stability and Excellent Ruggedness
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

XTAH75065G4





Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set VGS to the pinch-off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage (28V)
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DS}	150	Vdc
Gate--Source Voltage	V_{GS}	-10,+2	Vdc
Operating Voltage	V_{DD}	36	Vdc
Maximum Forward Gate Current @ $T_C = 25^{\circ}\text{C}$	I_{gmax}	16	mA
Storage Temperature Range	T_{stg}	-65 to +150	$^{\circ}\text{C}$
Case Operating Temperature	T_C	+150	$^{\circ}\text{C}$
Operating Junction Temperature(See note 1)	T_J	+225	$^{\circ}\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case $T_C = 85^{\circ}\text{C}$, RF CW operation	$R_{\theta JC}$	1.6	C/W

Table 3. Electrical Characteristics ($T_C = 25^{\circ}\text{C}$ unless otherwise noted)

DC Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8\text{V}$; $I_{DS} = 16\text{mA}$	V_{DSS}	150			V
Gate Threshold Voltage	$V_{DS} = 28\text{V}$, $I_D = 16\text{mA}$	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	$V_{DS} = 28\text{V}$, $I_{DS} = 100\text{mA}$, Measured in Functional Test	$V_{GS(Q)}$		-2.6		V

5.8-6.6GHz

Typical performance

Figure 2: Power Gain, Efficiency as function of Pout

XTAH75065G4H Class AB Vds= 28V, Idq=94.0mA
PulseWidth= 20us, DutyCycle= 10%, DEMO1

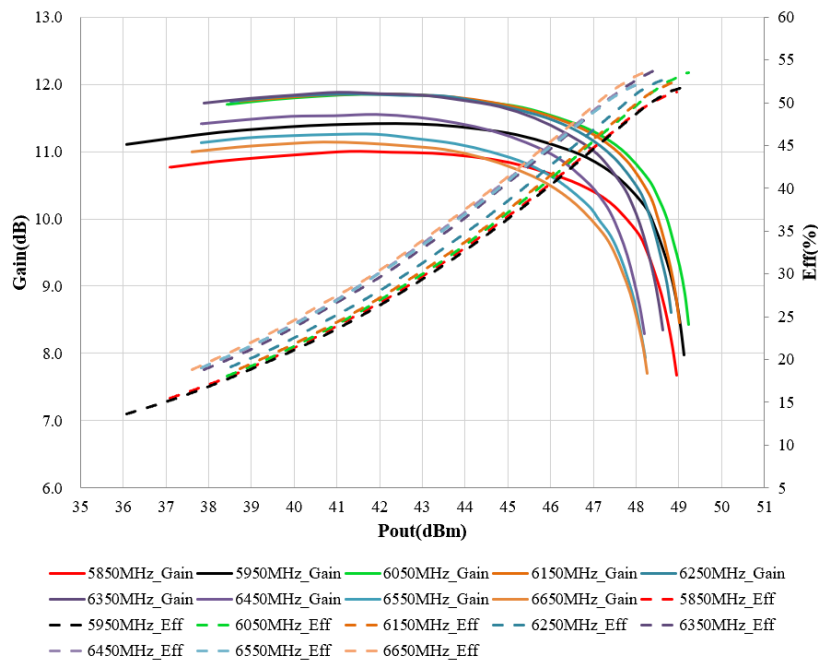
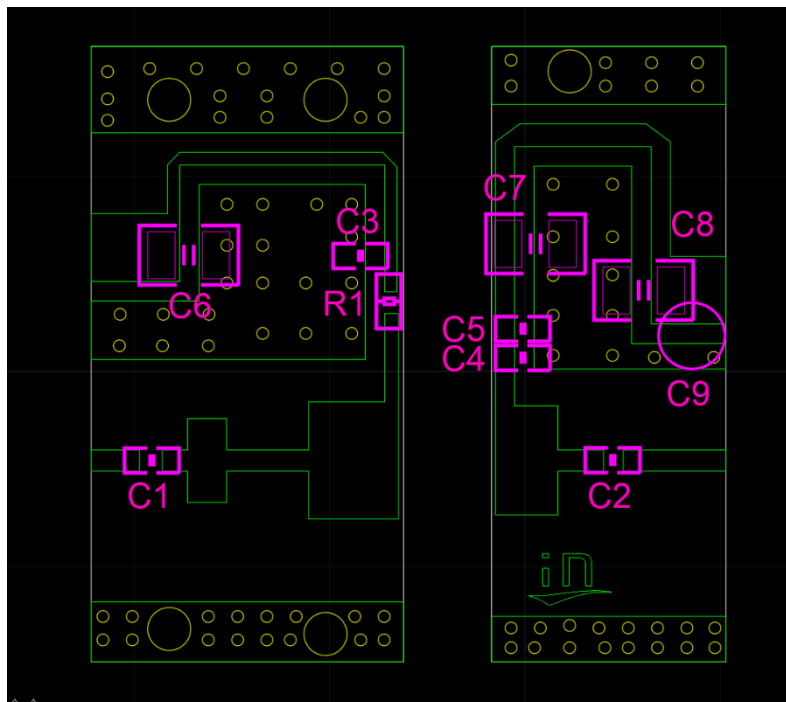


Figure 3: Picture and Bill of materials of application circuit
(Layout Gerber file upon request)





Component	Description	Quantity
U1	XTAH75065G4H	1
C1、 C2、 C3、 C4	1.8pF	4
C5	100pF	1
C6、 C7、 C8	10uF/63V	3
C9	470uF/63V	1
R1	10 Ω	1

6.9-7.4GHz

Figure 4: Power Gain, Efficiency as function of Pout

XTAH75065G4H Class AB Vds= 28V, Idq=5.6mA
PulseWidth= 20us, DutyCycle= 10%,DEMO1

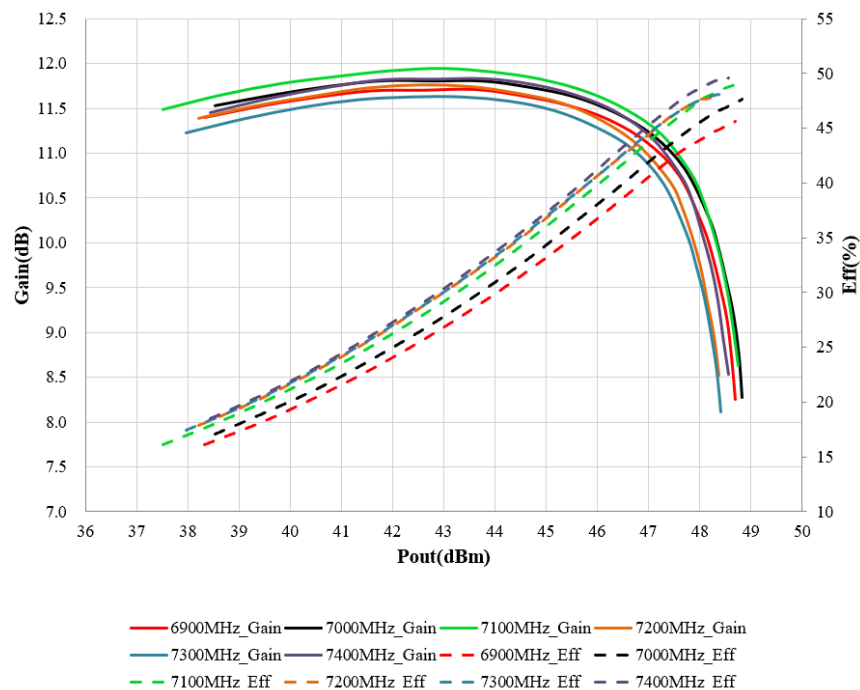
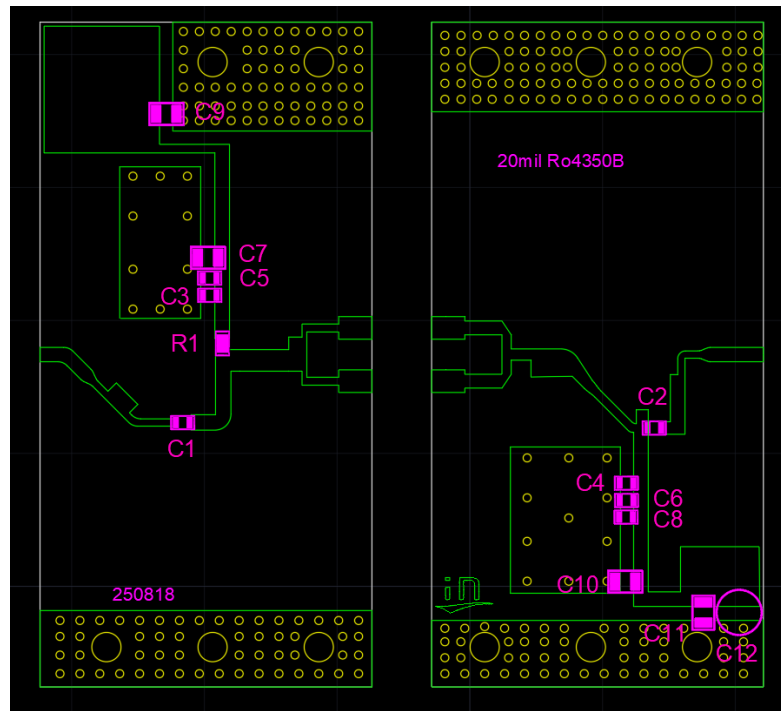


Figure 5: Picture and Bill of materials of application circuit
(Layout Gerber file upon request)



Component	Description	Quantity
U1	XTAH75065G4H	1
C1、 C2、 C3、 C4	1.8pF	4
C5、 C6	100pF	2
C7、 C9、 C10、 C11	10uF/63V	4
C8	10nF	1
C12	470uF/63V	1
R1	10 Ω	1



Package Outline

Ceramic package; 4 leads

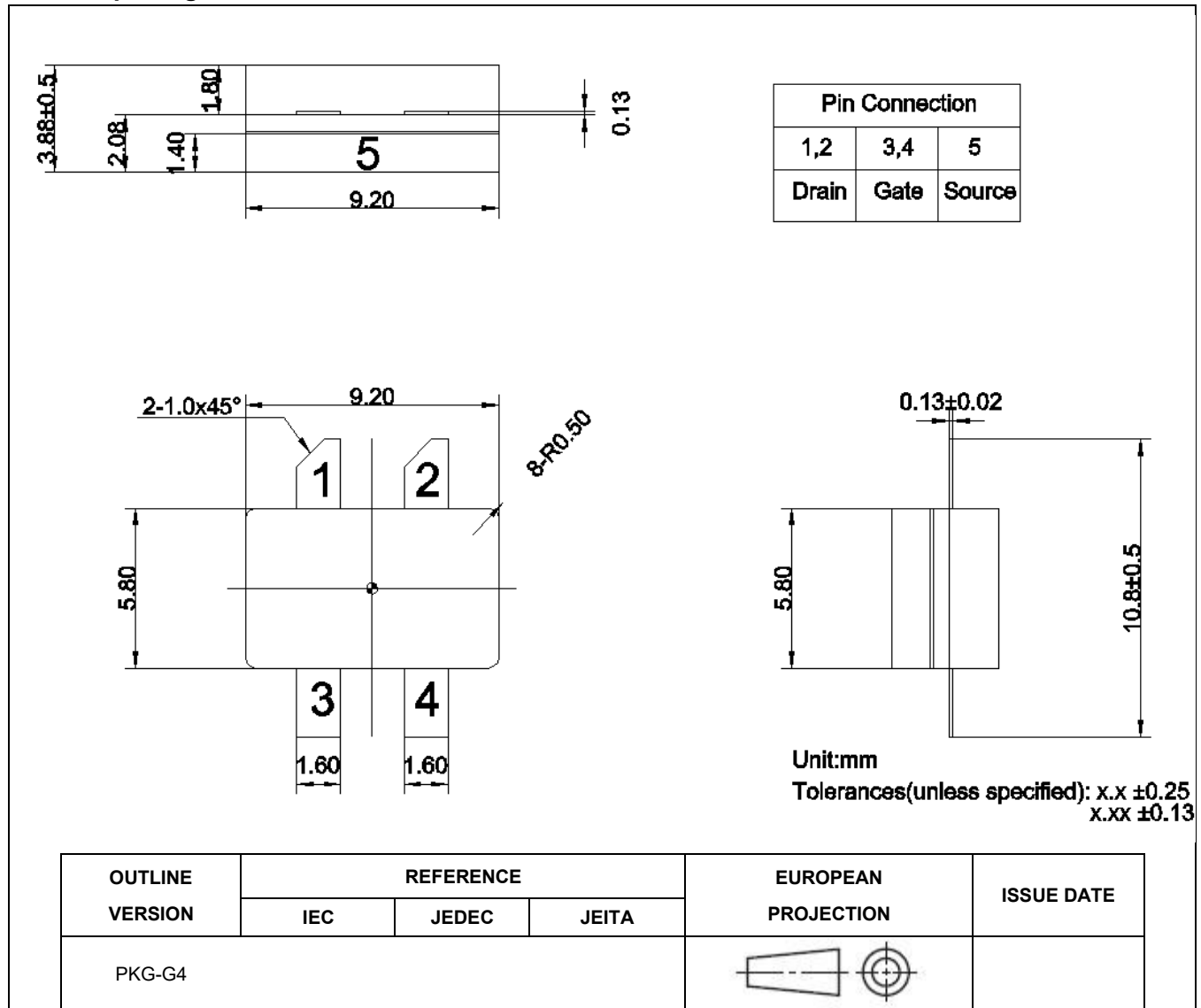


Figure 1. Package Outline PKG-G4



Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2025/9/2	V1.0	Preliminary Datasheet Creation

Application data based on ZYX-25-36/37

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